



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



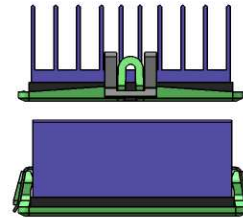
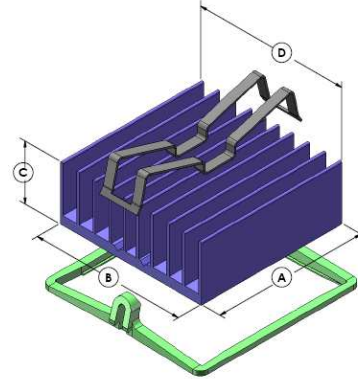


High Performance BGA Cooling Solutions with superGRIP™ Attachment

ATS PART # ATS-X53270G-C1-R0

Features & Benefits

- » Designed for 27 x 27 mm BGA components
- » superGRIP™ super strong, uniform attachment force helps achieve maximum performance from phase-changing TIM and does not require holes in the PCB
- » Allows the heat sink to be detached and reattached without damaging the component and/or the PCB, an important feature in the event a PCB may need to be reworked
- » Meets Telcordia GR-63-Core Office Vibration, ETSI 300 019 Transportation Vibration, and MIL-STD-810 Shock Testing and Unpackaged Drop Testing standards
- » Requires minimal space around the component's perimeter; ideal for densely populated PCBs
- » "Keep-Out" Requirements: An "Un-Populated" boarder zone of 3 mm around the component is necessary to facilitate the Installation/Removal of the superGRIP™. Please refer to the superGRIP™ Keep-Out Guidelines and superGRIP™ Installation/Removal Instructions for further details



**Image above is for illustration purposes only.*

Thermal Performance

AIR VELOCITY		THERMAL RESISTANCE	
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)
200	1.0	7.6	4.5
300	1.5	5.9	
400	2.0	5.1	
500	2.5	4.6	
600	3.0	4.2	
700	3.5	3.9	
800	4.0	3.7	

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
27 mm	27 mm	12.5 mm	27 mm	CHOMERICS T-766	BLUE ANODIZED

NOTES:

- 1) DIMENSIONS ARE MEASURED IN MILLIMETERS
- 2) DIMENSIONS A & B REFER TO COMPONENT SIZE
- 3) DIMENSION C = THE HEIGHT OF THE HEAT SINK SHOWN ABOVE AND DOES NOT INCLUDE THE HEIGHT OF THE ATTACHMENT METHOD
- 4) ATS RESERVES THE RIGHT TO UPDATE OR CHANGE IT PRODUCTS WITHOUT NOTICE
- 5) CONTACT ATS TO LEARN ABOUT CUSTOM OPTIONS AVAILABLE



ATS ADVANCED THERMAL SOLUTIONS, INC.
Innovations in Thermal Management®

For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).